

## ISTFA 2002: proceedings of the 28th International Symposium for Testing and Failure Analysis, 3-7 November 2002, Phoenix Civic Center, Phoenix, Arizona

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### Abstrak

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- Fault Localization and Functional Testing of ICs by Lock-in Thermography
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- A Study of Photoelectron Emission Microscopy Contrast Mechanisms Relevant to Microelectronics
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- Coax